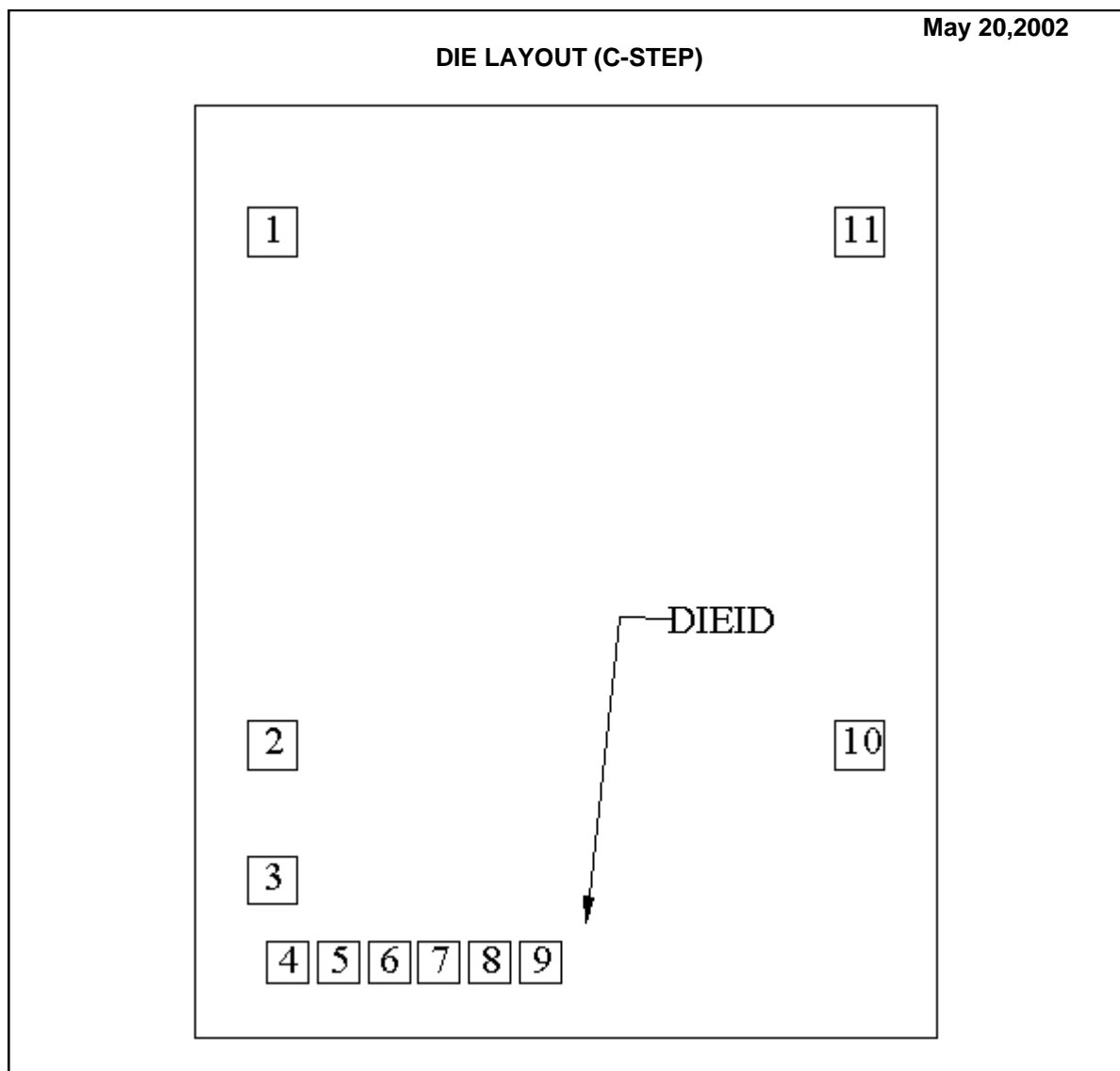


LMC6061I MDC MWC
PRECISION CMOS SINGLE MICROPOWER OPERATIONAL AMPLIFIER



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMC6061C	Bond Pad Opening Size (min)	92 μ m x 92 μ m
Die Step	C	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1397 μ m x 1753 μ m 55mils x 69mils	Back Side Connection	Floating
Thickness	330 μ m Nominal		
Min Pitch	95 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (C -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection						
SIGNAL	PAD#	X/Y CORRINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
INPUT -	1	-552	638	92	x	92
INPUT +	2	-552	-326	92	x	92
V-	3	-552	-580	92	x	92
NC	4	-523	-736	78	x	78
NC	5	-428	-736	78	x	78
NC	6	-334	-736	78	x	78
NC	7	-239	-736	78	x	78
NC	8	-144	-736	78	x	78
NC	9	-48	-736	78	x	78
OUTPUT	10	552	-326	92	x	92
V+	11	552	638	92	x	92

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